Unit:mm

C 0.2

NOT SOLDERED

\$4.4±0.2

LN124D

GaAlAs Red Light Emitting Diode

For Optical Fiber Communications and Control Systems

■ Features

• Red radiation: λ_P=660nm

• High-power output

High coupling characteristics used with plastic fiber

• High-speed modulation (10MHz)

• Plastic flat package: φ4.8

Item	Symbol	Value	Unit
Power Dissipation	Pp	120	mW
Forward Current (DC)	$I_{\mathbf{F}}$	40	mA
Pulse Forward Current	I _{FP} *	200	mA
Reverse Voltage (DC)	$V_{\mathbf{R}}$	3	OV C
Operating Ambient Temperature	T_{opr}	$-25 \sim +85$	
Storage Temperature	T _{stg}	-30~+100	, C

^{2-00.6±0.1} ■ Absolute Maximum Ratings (Ta=25°C) 1 : Cathode 2 : Anode

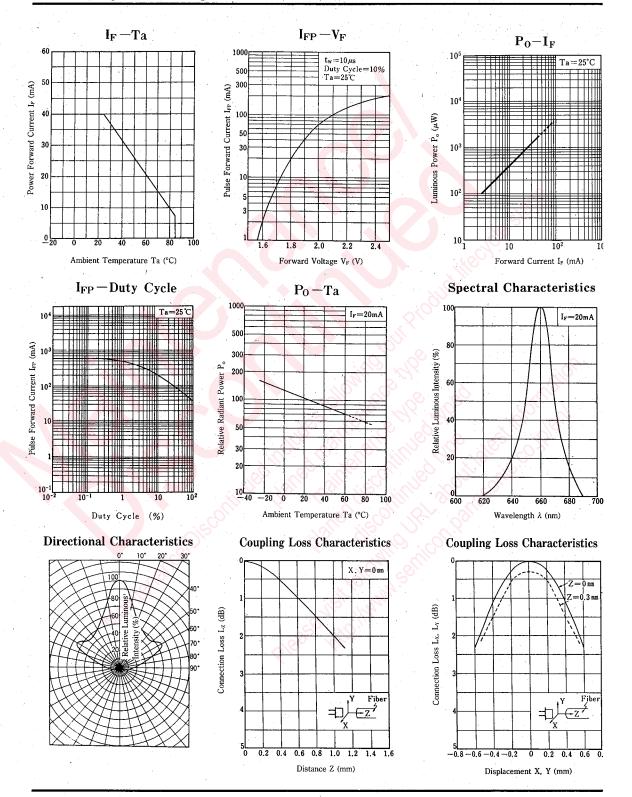
■ Electro-Optical Characteristics (Ta=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit
Optical Power Output	Po*	$I_F = 20 \mathrm{mA}$	400			μW
Peak Emission Wavelength	λp	$I_F = 20 \mathrm{mA}$	100	660		nm
Spectral Band Width	Δλ	I _E =20 mA	30.	20		nm
Forward Voltage (DC)	$V_{\rm F}$	I _F =20 mA		1.8	2.6	V
Reverse Current (DC)	IR	$V_R = 3V$		-	100	μA
Beam Half Angle	θ	Measured from the optical axis to the half power point		30		deg.
Response Time	t _r , t _f	$I_{FP} = 100 \text{mA}$		30		ns

* Po Classifications

Class	R	S	Т
P ₀ (μW)	400~900	700~1200	>1000

^{*}tw=10 \mus Duty Cycle=10 %



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